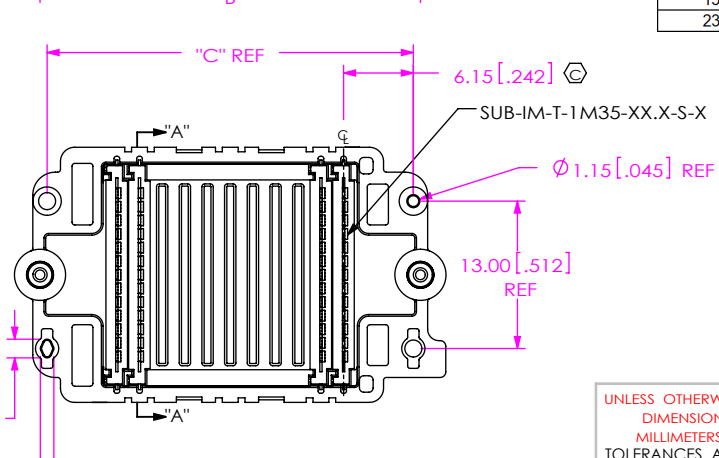
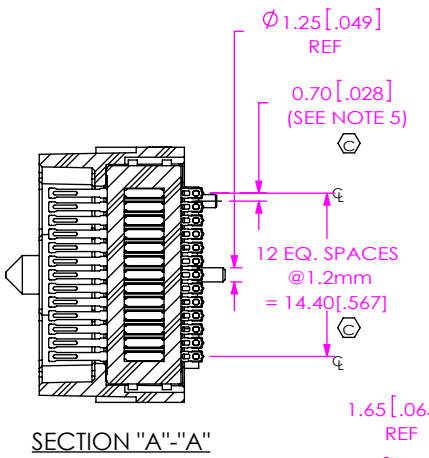
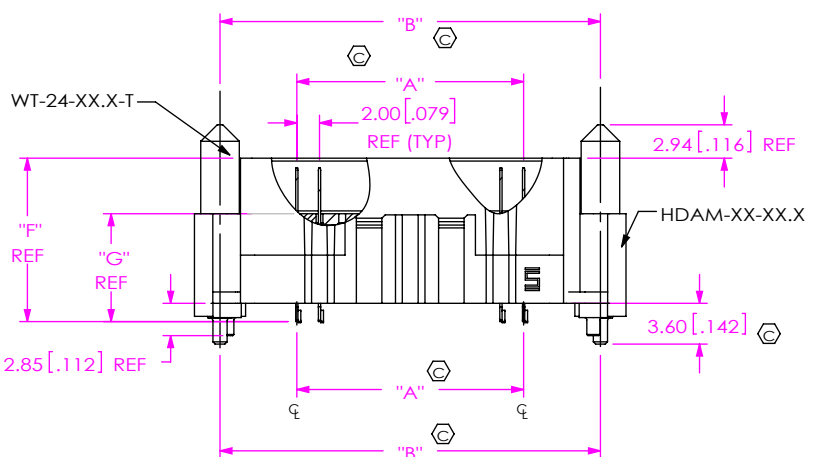
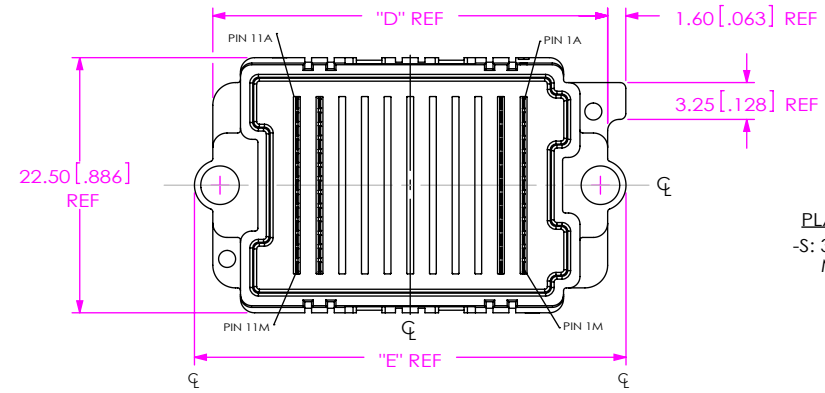


DO NOT SCALE FROM THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS  
(INCHES FOR REFERENCE ONLY)

HDAM-XX-XX.X-X-13-X-X-XX



No OF POSITIONS  
(13 ROW PER POSITION)  
-11  
-15  
-23

LEAD STYLE  
-12.0: 12MM  
-17.0: 17MM

PLATING SPECIFICATION  
-S: 30 μ" SELECTIVE GOLD IN MATING AREA,  
MATTE TIN ON TAIL AND GUIDE PINS

No OF ROWS  
-13

PACKAGING  
BLANK: TRAY (SEE NOTES 6 & 7)  
-TR: TAPE & REEL (SEE NOTES 7 & 8)  
-FR: FULL REEL QTY TAPE & REEL  
(SEE NOTES 7 & 8)

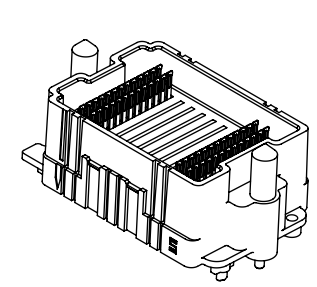
PICK & PLACE OPTION  
-P: PICK & PLACE PAD  
(USE MPP-26-01-N, SEE FIG 2, SHT 2)

SOLDER CHARGE MATERIAL  
-1: 63%TIN / 37% LEAD  
-2: 95.5% TIN / 3.8% SILVER  
0.7% COPPER (LEAD FREE)

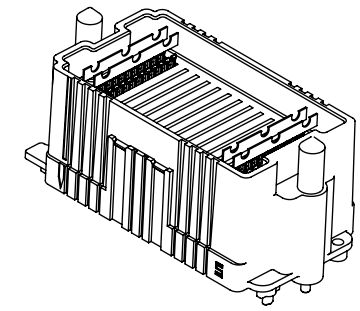
TABLE 2 STACK HEIGHT		
HDAM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

TABLE 1			
STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

TABLE 3								
No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12	20.0 [ .787 ]	33.55 [ 1.321 ]	32.30 [ 1.272 ]	34.82 [ 1.371 ]	38.06 [ 1.498 ]	14.41 [ .567 ]	9.51 [ .374 ]
15	12	28.0 [ 1.102 ]	41.55 [ 1.636 ]	40.30 [ 1.587 ]	42.82 [ 1.686 ]	46.06 [ 1.813 ]	14.41 [ .567 ]	9.51 [ .374 ]
23	12	44.0 [ 1.732 ]	57.55 [ 2.266 ]	56.30 [ 2.217 ]	58.82 [ 2.316 ]	62.06 [ 2.443 ]	14.41 [ .567 ]	9.51 [ .374 ]
11	17	20.0 [ .787 ]	33.55 [ 1.321 ]	32.30 [ 1.272 ]	34.82 [ 1.371 ]	38.06 [ 1.498 ]	19.41 [ .764 ]	14.51 [ .571 ]
15	17	28.0 [ 1.102 ]	41.55 [ 1.636 ]	40.30 [ 1.587 ]	42.82 [ 1.686 ]	46.06 [ 1.813 ]	19.41 [ .764 ]	14.51 [ .571 ]
23	17	44.0 [ 1.732 ]	57.55 [ 2.266 ]	56.30 [ 2.217 ]	58.82 [ 2.316 ]	62.06 [ 2.443 ]	19.41 [ .764 ]	14.51 [ .571 ]



(-12.0 SHOWN)



(-17.0 SHOWN)

- NOTES:
- ⊗ REPRESENTS A CRITICAL DIMENSION.
  - MINIMUM PUSHOUT FORCE: 2.22N [ .5 LB ]. FOR WAFERS
  - NOTE DELETED.
  - USE THESE SURFACES TO MEASURE "G" DIMENSION.
  - DIMENSION FROM ⌀ OF END TAIL TO ⌀ OF -A PIN.
  - TRAYS ARE STANDARD PACKAGING.
  - ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY STANDARDS (SPES) FOUND ON WWW.SAMTEC.COM.
  - ATTACH LABEL TO EACH REEL.

FIG 1  
-11: 11 POSITION  
(HDAM-11-12.0-X-13-X-X SHOWN)  
(SOME WAFERS NOT SHOWN FOR CLARITY)

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES].  
TOLERANCES ARE:  
DECIMALS ANGLES  
.X: ±0.3 [ .01 ]  
.XX: ±0.13 [ .005 ]  
.XXX: ±0.051 [ .0020 ]

MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1:5.1

INSULATOR: LCP. COLOR: BLACK  
CONTACT: COPPER ALLOY  
WAFER MATERIAL: LCP. COLOR: BLACK  
GUIDE PIN MATERIAL: BRASS  
PICK AND PLACE PAD: COPPER ALLOY

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**samtec**  
520 PARK EAST BLVD, NEW ALBANY, IN 47150  
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e-Mail info@SAMTEC.com code 55322

DESCRIPTION:  
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY  
DWG. NO.  
**HDAM-XX-XX.X-X-13-X-X-XX**  
BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 3

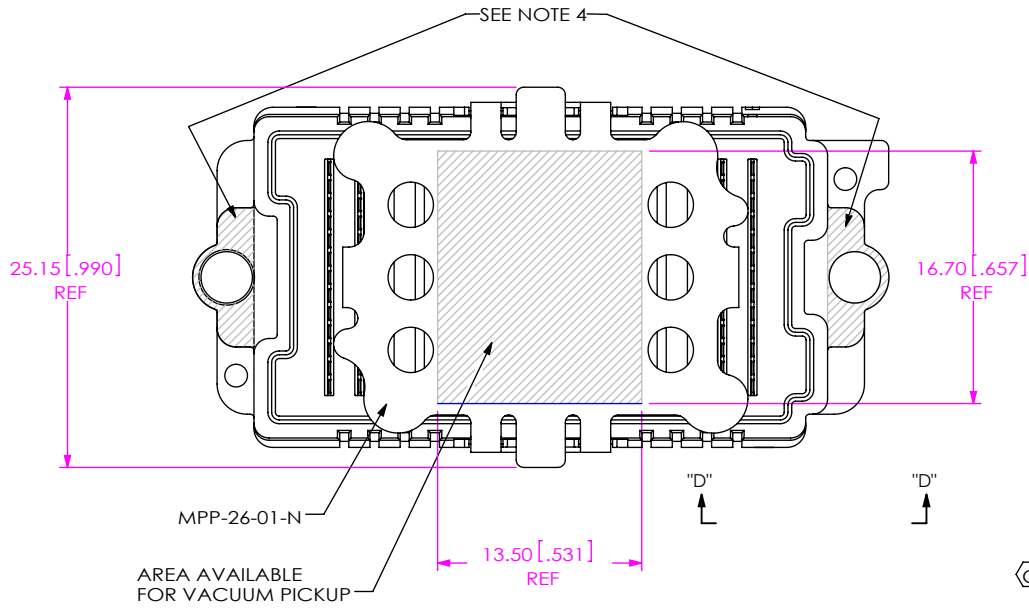
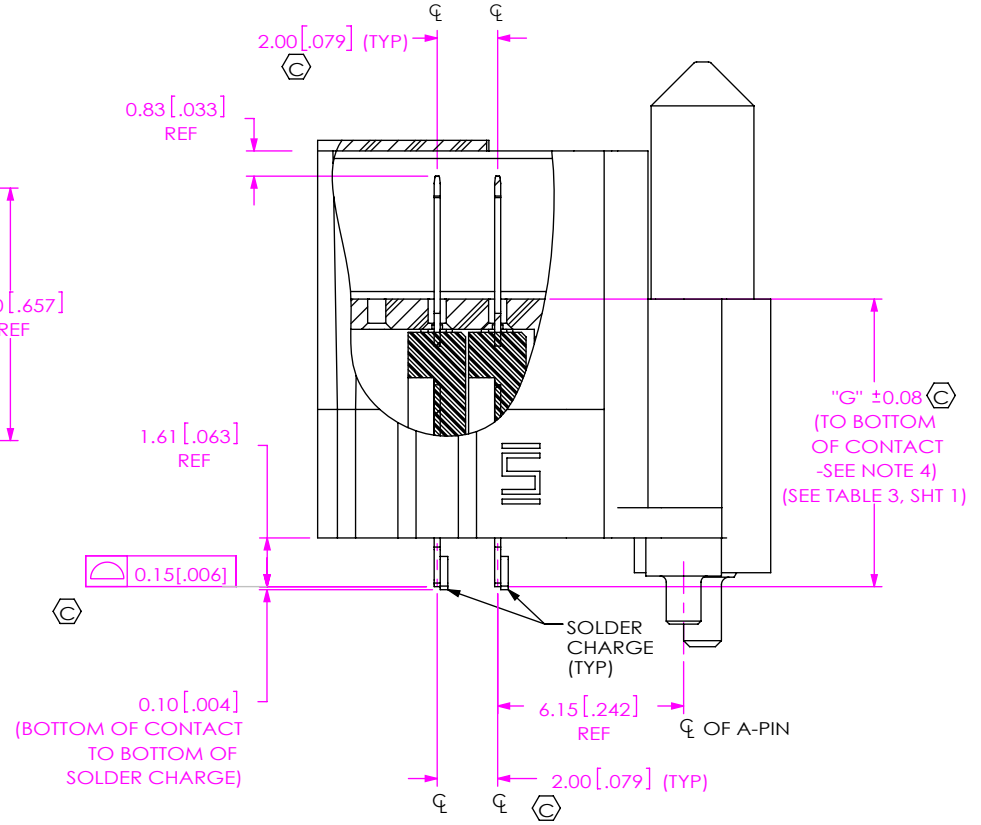
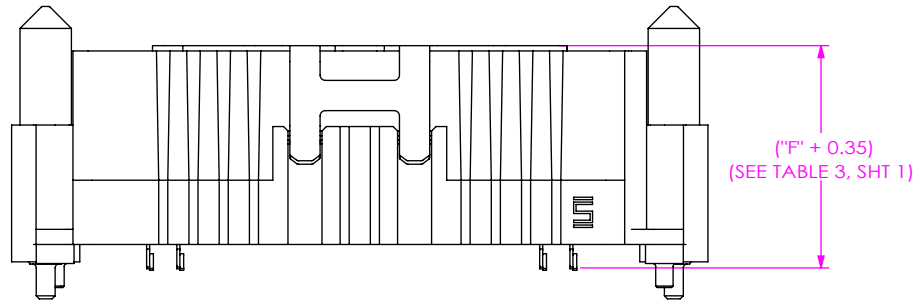


FIG 2  
-15: 15 POSITION  
(HDAM-15-12.0-X-13-X-P SHOWN)  
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW "D"- "D"  
SCALE 4:1

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1

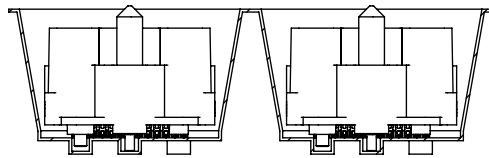
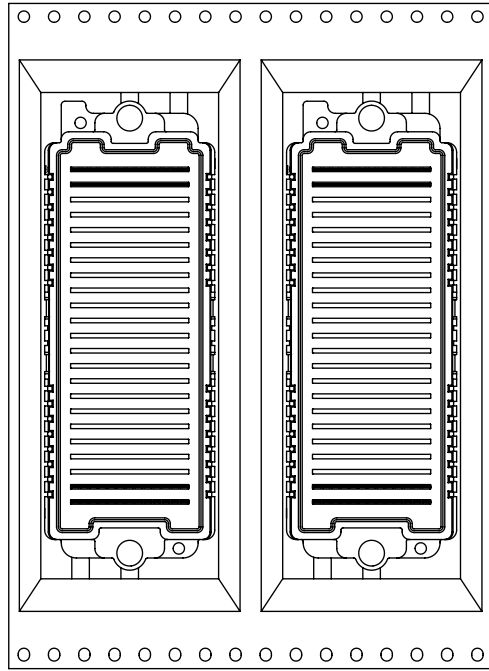


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e-Mail: info@SAMTEC.com code 55322

DESCRIPTION:  
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.  
HDAM-XX-XX.X-X-13-X-X-XX

BY:D KNOWLDEN 7/15/2005 SHEET 2 OF 3



USER DIRECTION OF UNREELING →  
POCKET NOT DETAILED

-TR PACKAGING VIEW

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DO NOT SCALE DRAWING

SHEET SCALE: 1:1



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e-Mail info@SAMTEC.com code 55322

DESCRIPTION:  
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.  
HDAM-XX-XX.X-X-13-X-X-XX

BY: D KNOWLDEN 7/15/2005 SHEET 3 OF 3